BTA208X series B

GENERAL DESCRIPTION

Glass passivated high commutation triacs in a full pack, plastic envelope intended for use in motor control circuits where high static and dynamic dV/dt and high dl/dt can occur. These devices will commutate the full rated rms current at the maximum rated junction temperature, without the aid of a snubber.

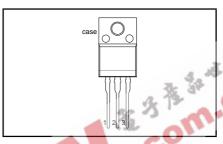
QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	MAX.	UNIT
V _{DRM} I _{T(RMS)} I _{TSM}	Repetitive peak off-state voltages RMS on-state current Non-repetitive peak on-state current	500B 500 8 65	600B 600 8 65	800B 800 8 65	V A A

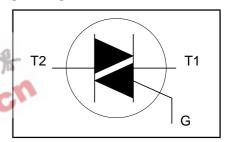
PINNING - SOT186A

PIN	PIN DESCRIPTION			
1	main terminal 1			
2	main terminal 2			
3	gate			
case	isolated			

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.		MAX.		UNIT
V_{DRM}	Repetitive peak off-state voltages			-600 600 ¹	-600 600 ¹	-800 800	V
I _{T(RMS)}	RMS on-state current	full sine wave;	-		8		A
I _{TSM}	Non-repetitive peak on-state current	$T_{hs} \le 73$ °C full sine wave; $T_j = 25$ °C prior to surge t = 20 ms t = 16.7 ms	-		65 71		A A
l²t dl _⊤ /dt	l ² t for fusing Repetitive rate of rise of on-state current after triggering	t = 10.7 ms t = 10 ms $I_{TM} = 12 \text{ A}; I_G = 0.2 \text{ A};$ $dI_G/dt = 0.2 \text{ A}/\mu\text{s}$	-	71 21 100		A ² s A/μs	
I _{GM} V _{GM} P _{GM} P _{G(AV)}	Peak gate current Peak gate voltage Peak gate power Average gate power	over any 20 ms period	-		2 5 5 0.5		A V W W
$T_{stg} T_{j}$	Storage temperature Operating junction temperature	, poniod	-40 -		150 125		°C °C

September 1997 1 Rev 1.200

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 6 $A/\mu s$.

Philips Semiconductors Product specification

Three quadrant triacs high commutation

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ISOLATION LIMITING VALUE & CHARACTERISTIC

 T_{hs} = 25 °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{isol}	R.M.S. isolation voltage from all three terminals to external heatsink	f = 50-60 Hz; sinusoidal waveform; R.H. ≤ 65%; clean and dustfree	-		2500	٧
C _{isol}	Capacitance from T2 to external heatsink	f = 1 MHz	-	10	-	pF

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-hs}	Thermal resistance junction to heatsink	full or half cycle with heatsink compound without heatsink compound			4.5 6.5	K/W K/W
R _{th j-a}	Thermal resistance junction to ambient	in free air	-	55	-	K/W

STATIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS		MIN.	TYP.	MAX.	UNIT
I _{GT}	Gate trigger current ²	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$					
0.	00		T2+ G+	2	18	50	mΑ
			T2+ G-	2	21	50	mΑ
			T2- G-	2	34	50	mΑ
I _I	Latching current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$					
_	, and the second	7 91	T2+ G+	-	31	60	mΑ
			T2+ G-	-	34	90	mΑ
			T2- G-	-	30	60	mΑ
I _H	Holding current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$		-	31	60	mΑ
$oldsymbol{V}_T$	On-state voltage	$I_{T} = 10 \text{ A}$		-	1.3	1.65	V
V_{GT}	Gate trigger voltage	$\dot{V}_{D} = 12 \text{ V}; I_{T} = 0.1 \text{ A}$		-	0.7	1.5	V
		$V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_i = 125$	5 °C	0.25	0.4	-	V
I_D	Off-state leakage current	$V_D = V_{DRM(max)}$; $T_j = 125 °C$		-	0.1	0.5	mA

DYNAMIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
dV _D /dt	Critical rate of rise of	$V_{DM} = 67\% V_{DRM(max)}; T_j = 125 °C;$	1000	4000	-	V/μs
dl _{com} /dt	off-state voltage Critical rate of change of commutating current	exponential waveform; gate open circuit $V_{DM} = 400 \text{ V}$; $T_j = 125 \text{ °C}$; $I_{T(RMS)} = 8 \text{ A}$; without snubber; gate open circuit	-	14	-	A/ms
$\mathbf{t}_{ ext{gt}}$		$I_{TM} = 12 \text{ A}; V_D = V_{DRM(max)}; I_G = 0.1 \text{ A};$ $dI_G/dt = 5 \text{ A}/\mu\text{s}$	-	2	-	μs

² Device does not trigger in the T2-, G+ quadrant.

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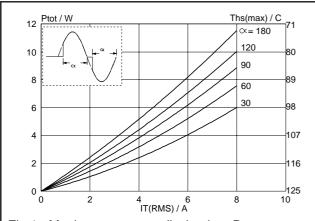


Fig.1. Maximum on-state dissipation, P_{tot} , versus rms on-state current, $I_{T(RMS)}$, where α = conduction angle.

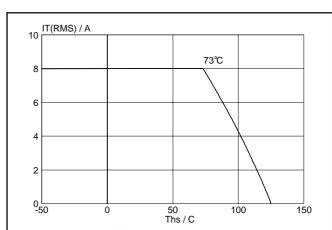


Fig.4. Maximum permissible rms current $I_{T(RMS)}$, versus heatsink temperature T_{hs} .

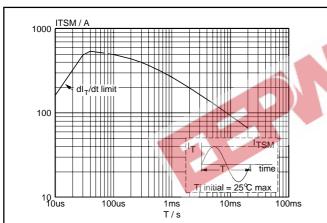


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \le 20$ ms.

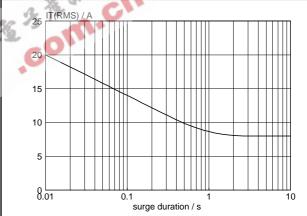


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{hs} \le 73$ °C.

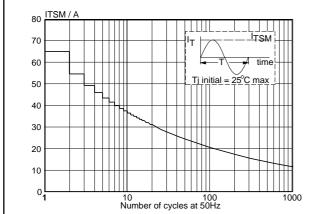


Fig.3. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, f = 50 Hz.

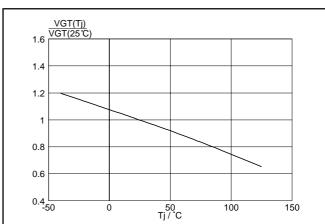
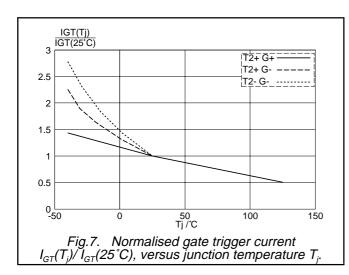


Fig.6. Normalised gate trigger voltage $V_{GT}(T_j)/V_{GT}(25^{\circ}C)$, versus junction temperature T_{j} .

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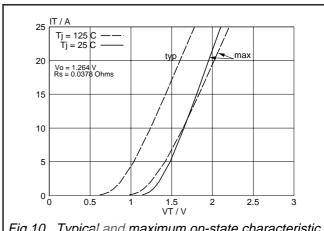
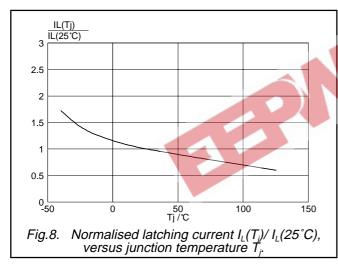
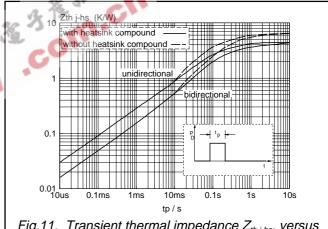


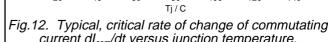
Fig. 10. Typical and maximum on-state characteristic.





IH(Tj) 3 IH(25°C) 0.5 0 50 50 Tj /℃ 150

Fig.11. Transient thermal impedance $Z_{th j-hs}$, versus pulse width t_o.



100

Normalised holding current $I_H(T_i)/I_H(25^{\circ}C)$, versus junction temperature T_j . Fig.12. Typical, critical rate of change of commutating current dl_{com}/dt versus junction temperature.

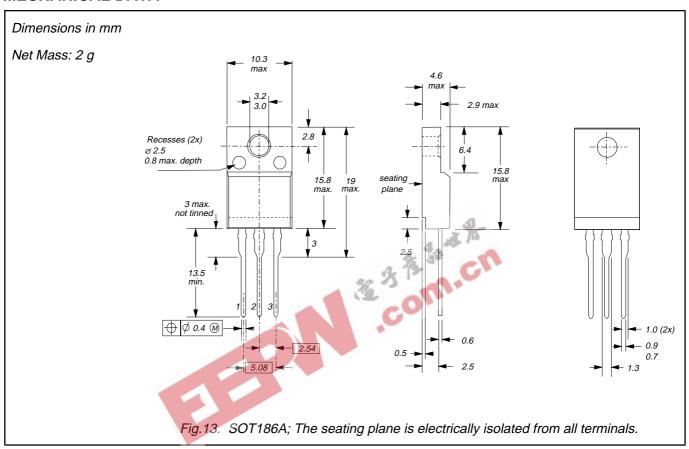
dlcom/dt (A/ms)

1000

100

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MECHANICAL DATA



- Notes
 1. Refer to mounting instructions for F-pack envelopes.
 2. Epoxy meets UL94 V0 at 1/8".

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DEFINITIONS

Data sheet status					
Objective specification	This data sheet contains target or goal specifications for product development.				
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.				
Product specification	This data sheet contains final product specifications.				
Limiting values					

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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